

/ Descriptions

KF \$) CD E GE Silicon NPN transistor in a TO-92LM Plastic Package.

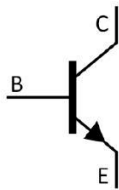
/ Features

High breakdown voltage, low output capacitance, high f_T .

/ Applications

TV video output, high voltage switching and driver stage of audio amplifier applications.

/ Equivalent Circuit



/ Pinning



PIN1 Base PIN 2 Collector PIN 3 Emitter

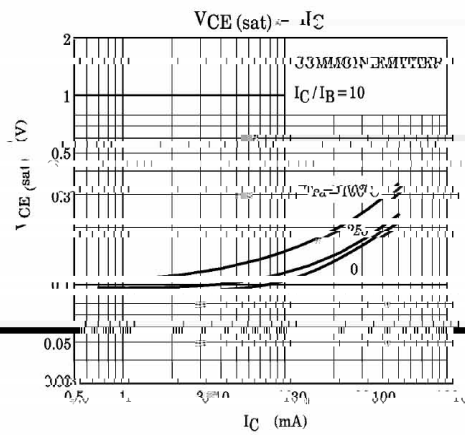
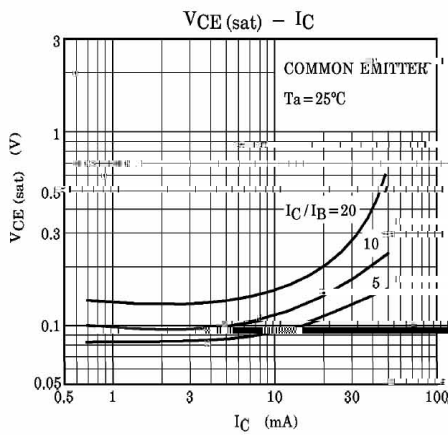
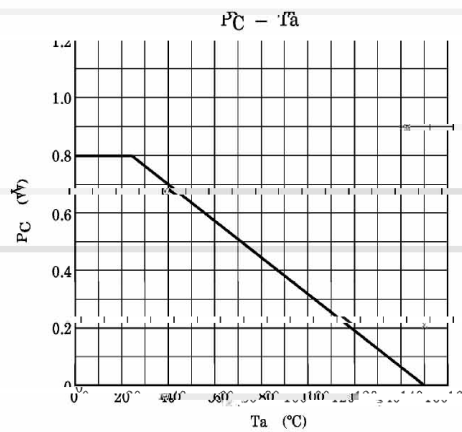
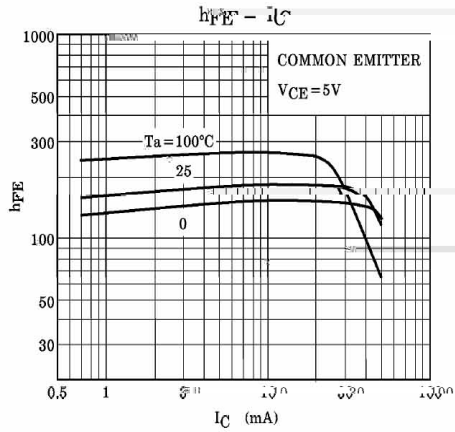
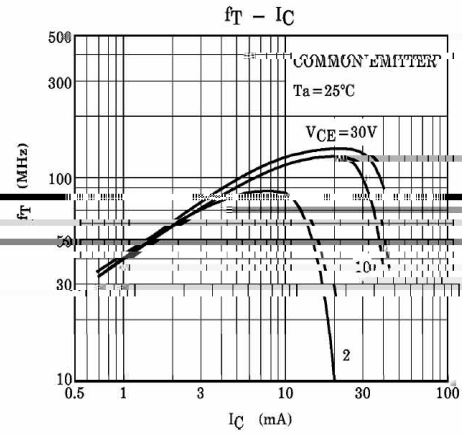
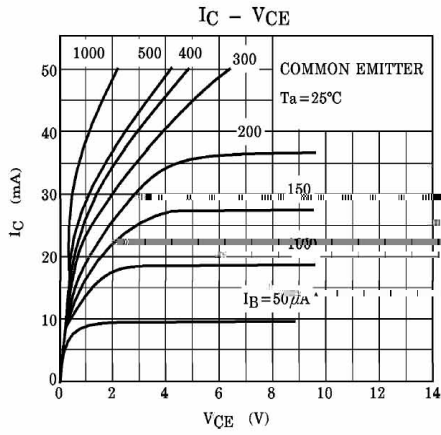
/ h_{FE} Classifications & Marking

h_{FE} Classifications Symbol	O	Y
h_{FE} Range	70 140	120 240

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	200	V
Collector to Emitter Voltage	V_{CEO}	150	V
Emitter to Base Voltage	V_{EBO}	5.0	V
Collector Current (DC)	I_C	50	mA
Emitter Current	I_E	-50	mA
Collector Power Dissipation	P_C	800	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector Cut-Off Current	I_{CBO}	$V_{CB}=200V$ $I_E=0$			0.1	μA
Emitter Cut-Off Current	I_{EBO}	$V_{EB}=5.0V$ $I_C=0$			0.1	μA
DC Current Gain	h_{FE}					

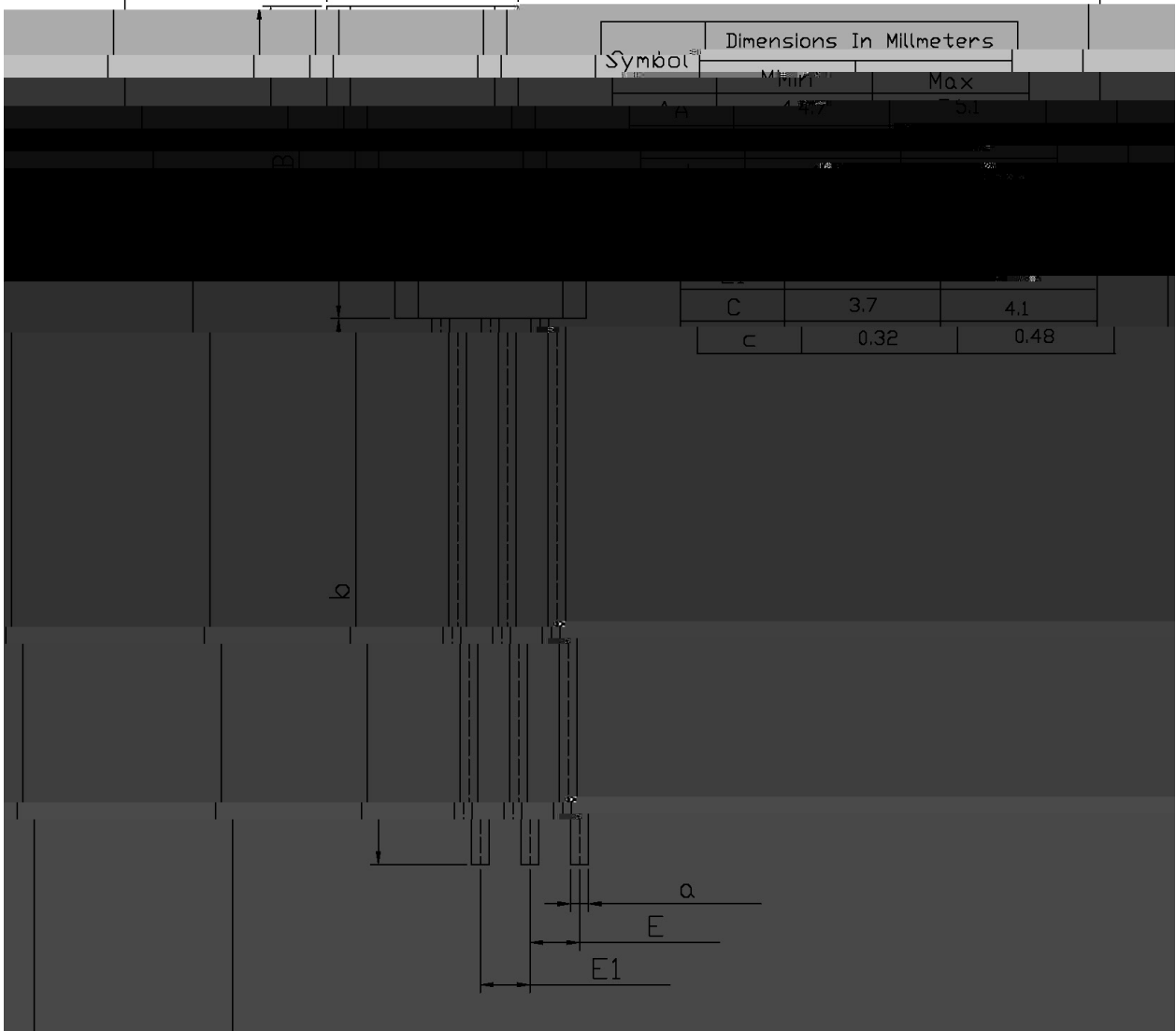
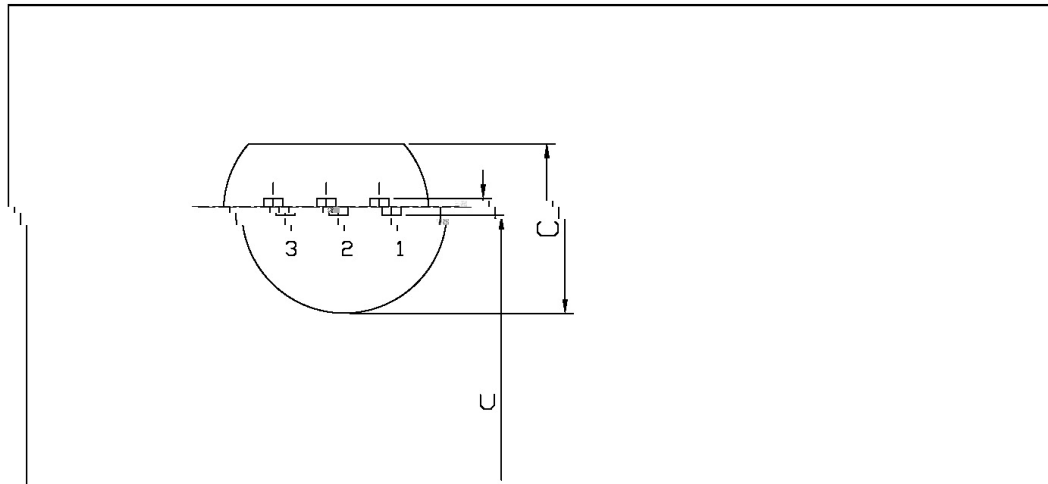
/ Electrical Characteristic Curve



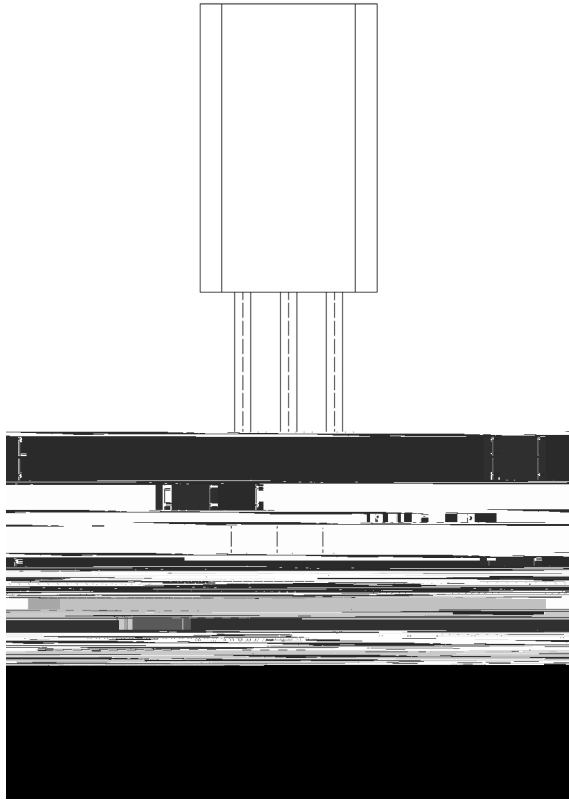
/ Package Dimensions

TO-92LM

Unit: mm

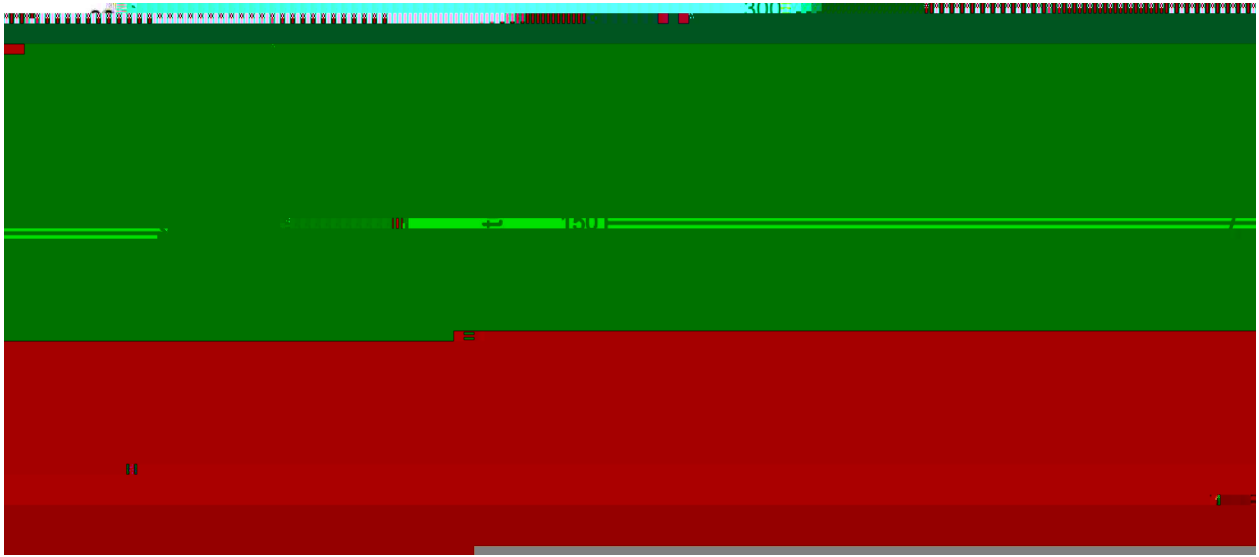


/ Marking Instructions



91 1
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() / Temperature Profile for Dip Soldering(Pb-Free)



1	25	150	60	90sec;	Note:	1.Preheating:25~150 , Time:60~90sec.
2	255..5		5..0.5sec;		2.Peak Temp.:255..5 , Duration:5..0.5sec.	
3			2	10 /sec.	3. Cooling Speed: 2~10 /sec.	

/ Resistance to Soldering Heat Test Conditions

270..5	10..1 sec.	Temp.:270±5	Time:10±1 sec
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/ Packaging SPEC.

/ BULK